

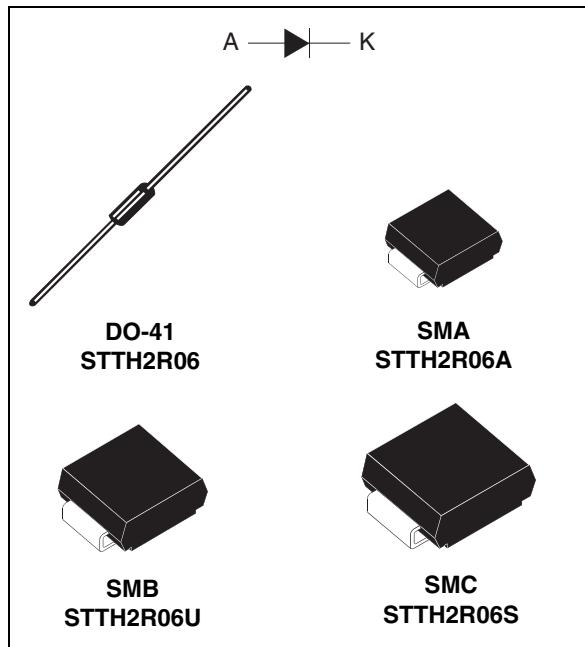
## High efficiency ultrafast diode

### Features

- Very low conduction losses
- Negligible switching losses
- Low forward and reverse recovery times
- High junction temperature

### Description

The STTH2R06 uses ST Turbo 2 600 V planar Pt doping technology. It is specially suited for switching mode base drive and transistor circuits. Packaged in axial, SMA, SMB and SMC, this device is intended for use in high frequency inverters, free wheeling and polarity protection.



**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	2 A
$V_{RRM}$	600 V
$T_j$	175 °C
$V_F(\text{typ})$	1.0 V
$t_{rr} (\text{typ})$	35 ns

# 1 Characteristics

**Table 2. Absolute ratings (limiting values)**

Symbol	Parameter			Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage			600	V	
$I_{F(RMS)}$	Forward rms current			7	A	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	DO-41	$T_L = 70 \text{ }^\circ\text{C}$	2	A	
		SMA	$T_L = 85 \text{ }^\circ\text{C}$			
		SMB	$T_L = 100 \text{ }^\circ\text{C}$			
		SMC	$T_L = 115 \text{ }^\circ\text{C}$			
$I_{FSM}$	Surge non repetitive forward current	DO-41	$t_p = 10\text{ms}$ sinusoidal	40	A	
		SMA / SMB / SMC		30		
$T_{stg}$	Storage temperature range			-65 to + 175	$^\circ\text{C}$	
$T_j$	Operating junction temperature range			-40 to + 175	$^\circ\text{C}$	

**Table 3. Thermal resistance**

Symbol	Parameter	Maximum	Unit
$R_{th(j-l)}$	Junction to lead	DO-41 L = 5 mm	35
		SMA	30
		SMB	25
		SMC	20

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25 \text{ }^\circ\text{C}$	$V_R = V_{RRM}$	-	-	2
		$T_j = 150 \text{ }^\circ\text{C}$		-	12	85
$V_F^{(2)}$	Forward voltage drop	$T_j = 25 \text{ }^\circ\text{C}$	$I_F = 2 \text{ A}$	-	-	1.7
		$T_j = 150 \text{ }^\circ\text{C}$		-	1.0	1.25

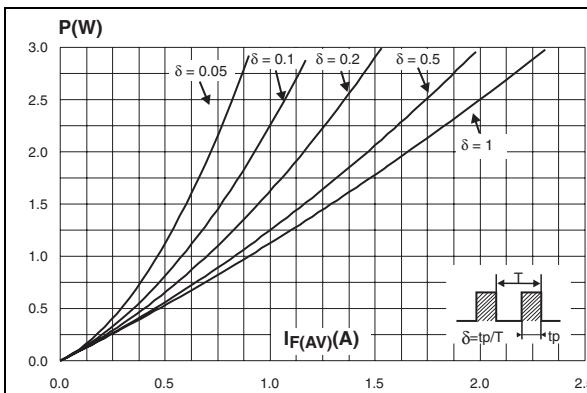
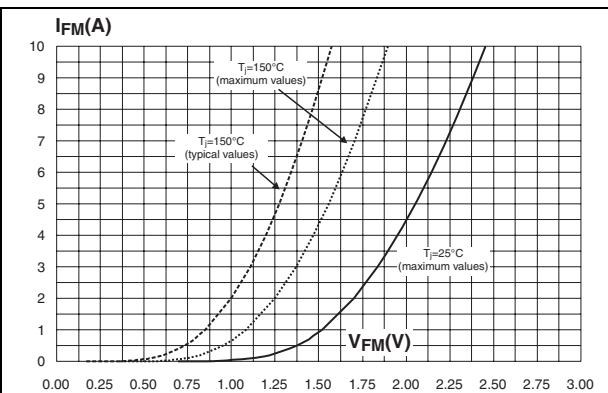
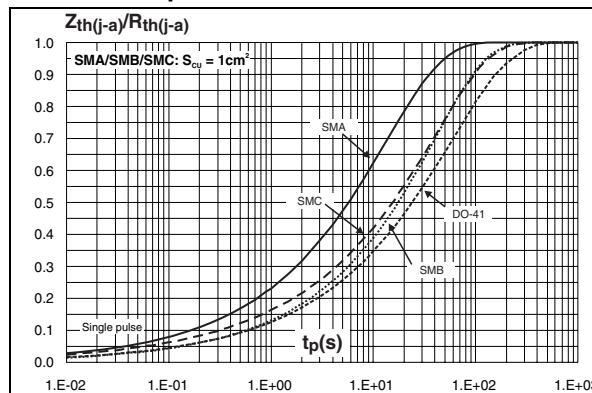
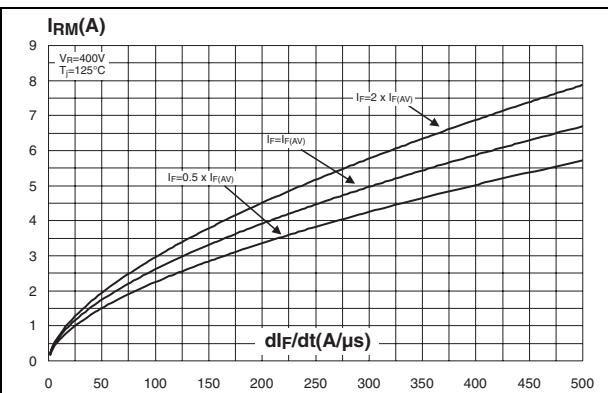
1. Pulse test:  $t_p = 5 \text{ ms}$ ,  $\delta < 2 \%$
2. Pulse test:  $t_p = 380 \mu\text{s}$ ,  $\delta < 2 \%$

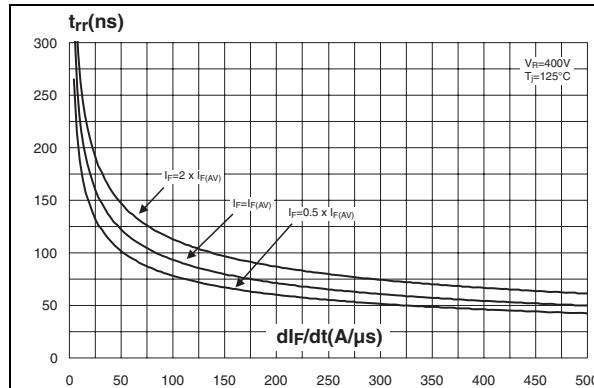
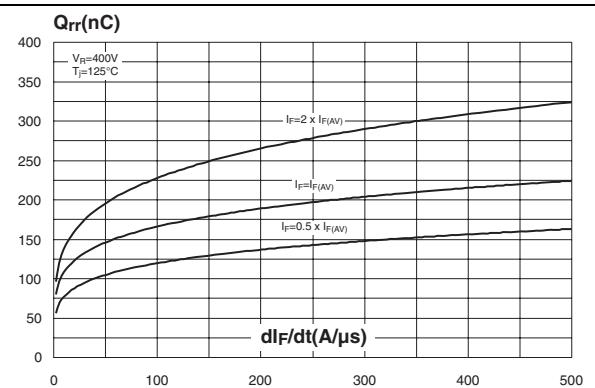
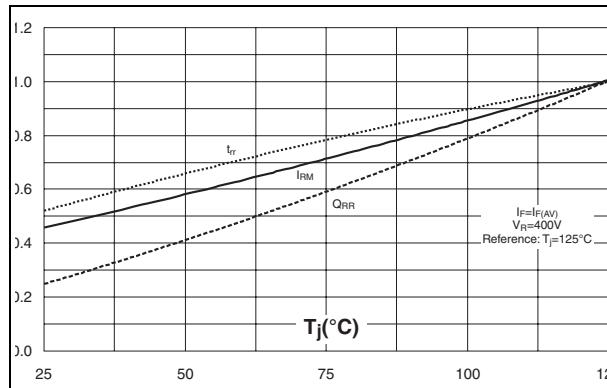
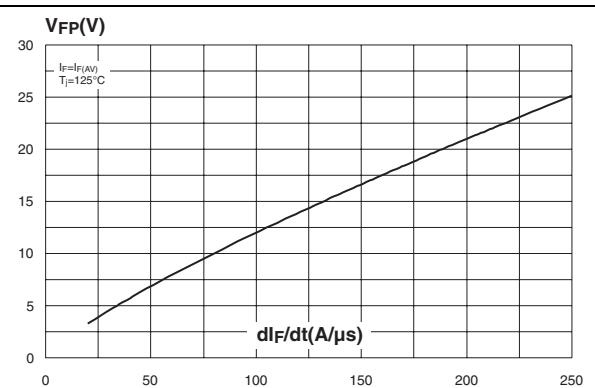
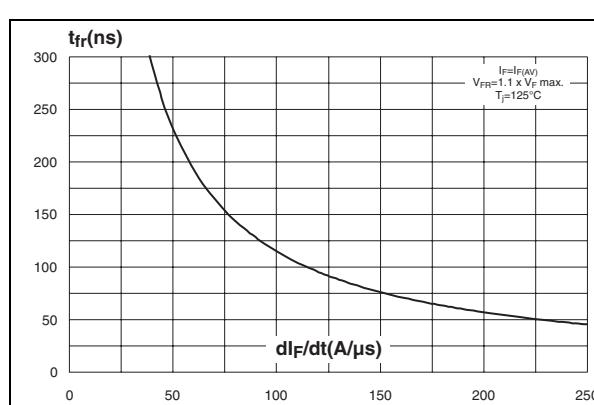
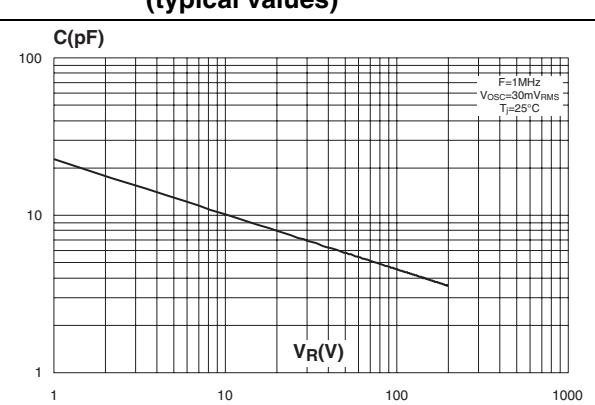
To evaluate the maximum conduction losses use the following equation:

$$P = 1 \times I_{F(AV)} + 0.125 I_{F(RMS)}^2$$

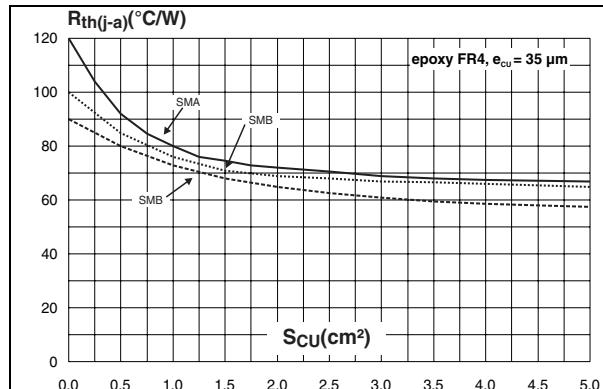
**Table 5. Dynamic electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25^\circ\text{C}$	$I_F = 0.5 \text{ A}, I_{rr} = 0.25 \text{ A}, I_R = 1 \text{ A}$	-	-	30
			$I_F = 1 \text{ A}, dI_F/dt = -50 \text{ A}/\mu\text{s}, V_R = 30 \text{ V}$	-	35	50
$t_{fr}$	Forward recovery time	$T_j = 25^\circ\text{C}$	$I_F = 2 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$	-	-	100
$V_{FP}$	Forward recovery voltage		$V_{FR} = 1.1 \times V_{F\max}$	-	-	10
						V

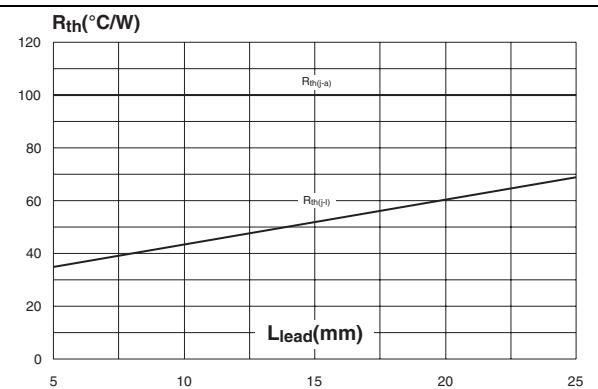
**Figure 1. Conduction losses versus average forward current****Figure 2. Forward voltage drop versus forward current****Figure 3. Relative variation of thermal impedance junction to case versus pulse duration****Figure 4. Peak reverse recovery current versus  $dI_F/dt$  (typical values)**

**Figure 5. Reverse recovery time versus  $di_F/dt$  (typical values)****Figure 6. Reverse recovery charges versus  $di_F/dt$  (typical values)****Figure 7. Relative variations of dynamic parameters versus junction temperature****Figure 8. Transient peak forward voltage versus  $di_F/dt$  (typical values)****Figure 9. Forward recovery time versus  $di_F/dt$  (typical values)****Figure 10. Junction capacitance versus reverse voltage applied (typical values)**

**Figure 11. Thermal resistance junction to ambient versus copper surface under each lead**



**Figure 12. Thermal resistance versus lead length (DO-41)**



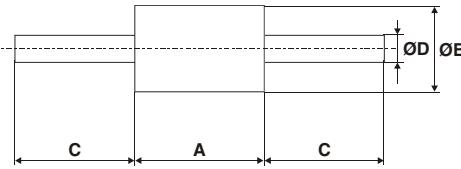
## 2 Package information

- Epoxy meets UL 94, V0
- Band indicates cathode
- Bending method (DO-41): see Application note AN1471

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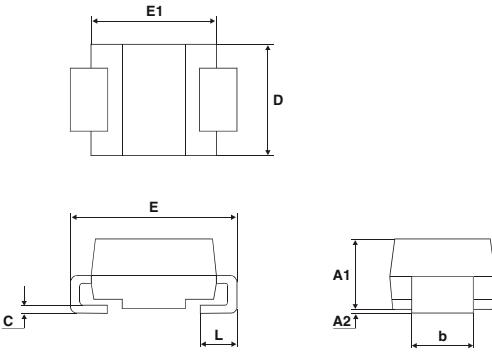
**Table 6. DO-41 (plastic) dimensions**

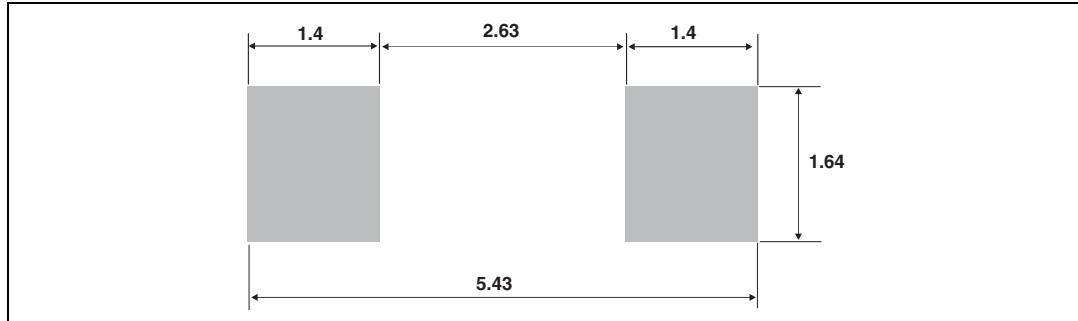
Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.07	5.20	0.160	0.205
B	2.04	2.71	0.080	0.107
C	25.4		1	
D	0.71	0.86	0.028	0.034



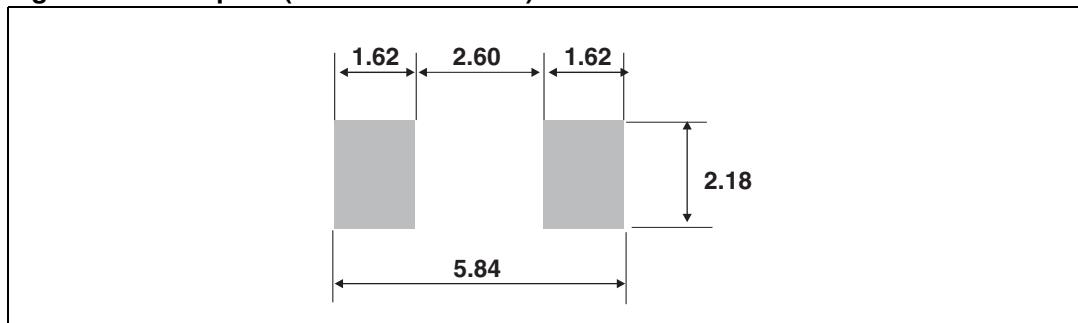
**Table 7. SMA dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059



**Figure 13. Footprint (dimensions in mm)****Table 8. SMB dimensions**

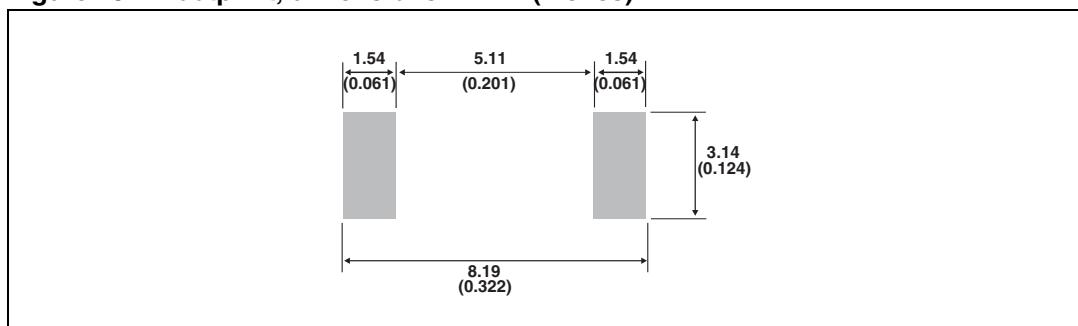
Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.50	0.030	0.059

**Figure 14. Footprint (dimensions in mm)**

**Table 9. SMC dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b <sup>(1)</sup>	2.90	3.20	0.114	0.126
c <sup>(1)</sup>	0.15	0.40	0.006	0.016
D	5.55	6.25	0.218	0.246
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
L	0.75	1.50	0.030	0.059

1. Dimensions b and c apply to plated leads

**Figure 15. Footprint, dimensions in mm (inches)**

### 3 Ordering information

**Table 10. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH2R06	STTH2R06	DO-41	0.34 g	2000	Ammopack
STTH2R06RL	STTH2R06	DO-41	0.34 g	5000	Tape and reel
STTH2R06A	R6A	SMA	0.068 g	5000	Tape and reel
STTH2R06U	R6U	SMB	0.11 g	2500	Tape and reel
STTH2R06S	R62	SMC	0.243 g	2500	Tape and reel

### 4 Revision history

**Table 11. Document revision history**

Date	Revision	Changes
07-Sep-2004	1	First issue
1-Jun-2005	2	SMC package addition.
30-Sep-2009	3	Updated <a href="#">Table 6</a> package dimensions.
04-Dec-2009	4	Updated <a href="#">Table 9</a> package dimensions.

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